

Minimum prepreg thickness

Minimum prepreg thickness – this parameter characterises the thinnest prepreg used by Brandner Electronics in the manufacture of multilayer printed circuit boards.

It indicates the thickness achieved after pressing the multilayer package. **After pressing, the thickness may vary by +/- 10% and it depends on the topography of the inner layers**, i.e. the area of inner layers covered with copper, the thickness of the copper foil, etc.

Brandner Electronics uses the following prepregs in its manufacture processes:

Type	Thickness
1080	0.063mm
2116	0.110mm
7628	0.180mm

During design, particularly in the case of printed circuit boards with a controlled impedance, it is necessary to clarify which prepregs the manufacturer has and use these specific prepregs.

During design, there is no point in making up or consenting to non-existent prepreg thicknesses installed in the CAD program (e.g. 0.126 mm).